

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT | |
| NATURE OF CONVEYANCE: | ASSIGNMENT | |
| CONVEYING PARTY DATA | | |
| | Name | Execution Date |
| | SUKEHIRO YAMAMOTO | 08/02/2017 |
| RECEIVING PARTY DATA | | |
| Name: | SII SEMICONDUCTOR CORPORATION | |
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| City: | CHIBA-SHI, CHIBA | |
| State/Country: | JAPAN | |
| Postal Code: | 261-8507 | |
| PROPERTY NUMBERS Total: 1 | | |
| | Property Type | Number |
| | Application Number: | 15670504 |
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| DATE SIGNED: | 08/07/2017 | |
| Total Attachments: 2 | | |
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| source=15670504asg#page2.tif | | |

ASSIGNMENT

WHEREAS, I, Sukehiro YAMAMOTO residing at c/o SII Semiconductor Corporation, 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, 261-8507, Japan, have invented new and useful improvements in POLISHING HEAD, CMP APPARATUS INCLUDING A POLISHING HEAD, AND MANUFACTURING METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE USING A CMP APPARATUS, for which I have prepared an application for Letters Patent of the United States of America;

AND WHEREAS, SII Semiconductor Corporation, a Japanese corporation located and doing business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, 261-8507, Japan, is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor;

NOW, THEREFORE, be it known by all whom it may concern, that for and in consideration of Ten Dollars (\$10.00) and other good and valuable consideration to me in hand paid, the receipt of which is hereby acknowledged, I have assigned, sold and transferred and by these presents do hereby assign, sell and transfer unto the said SII Semiconductor Corporation for the territory of the United States of America, my entire right, title and interest in and to the said invention, and in and to the said application, prepared and executed by me on August 2, 2017, filed August 7, 2017, Application No. 15/670,504, preparatory to obtaining Letters Patent thereon and in and to any and all divisions, reissues and continuations thereof, and in and

to any Letters Patent that may be granted thereon; said invention, application and Letters Patent to be held and enjoyed by the said SII Semiconductor Corporation, its legal representatives and assigns, as fully and entirely as the same would have been held by me had this assignment, sale and transfer not been made.

AND, I hereby covenant and agree that I will at any time upon the request and at the expense of said assignee execute and deliver any and all papers and do all lawful acts that may be necessary or desirable to perfect the title to said invention and to obtain Letters Patent therefor, and I hereby authorize and request the Honorable Commissioner of Patents and Trademarks to issue the said Letters Patent to the said SII Semiconductor Corporation in accordance with this assignment.

Executed this 2nd day of August, 2017.

Witness:

Sukehiro Yamamoto (L.S.)
Sukehiro YAMAMOTO